

# **A 28nm High-Density 6T SRAM with Optimized Peripheral-Assist Circuits for Operation down to 0.6V**

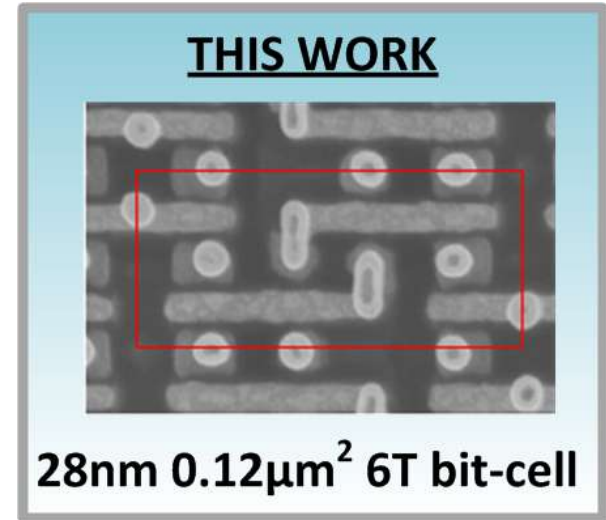
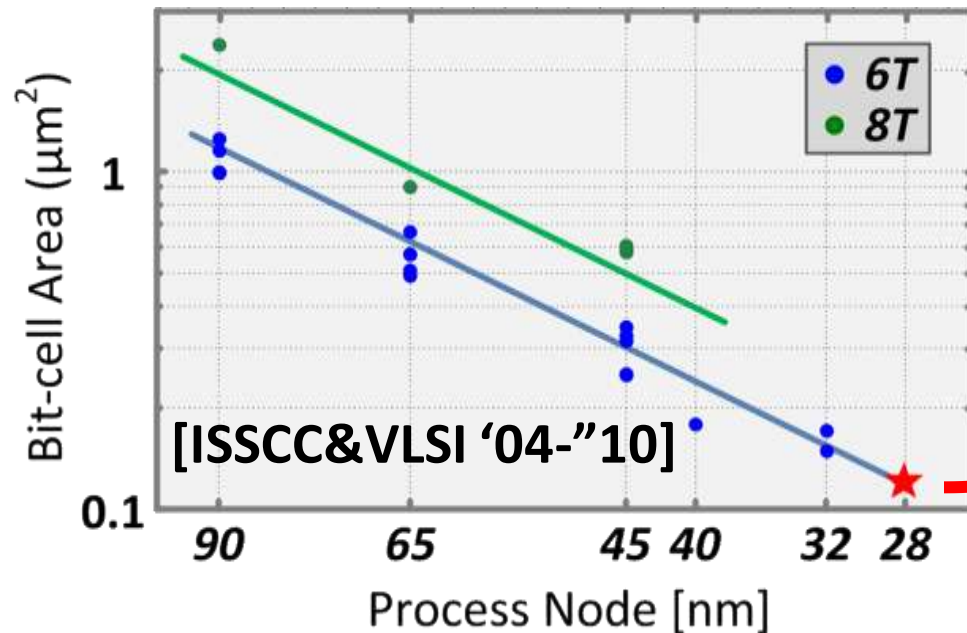
Mahmut E. Sinangil<sup>1</sup>, Hugh Mair<sup>2</sup>,  
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<sup>1</sup>Massachusetts Institute of Technology

<sup>2</sup>Texas Instruments, Incorporated

ISSCC 2011

# 6T vs. 8T Bit-cell



- **8T cell is a good low-voltage alternative at the expense of larger area**
  - *e.g. 40% larger cell area*

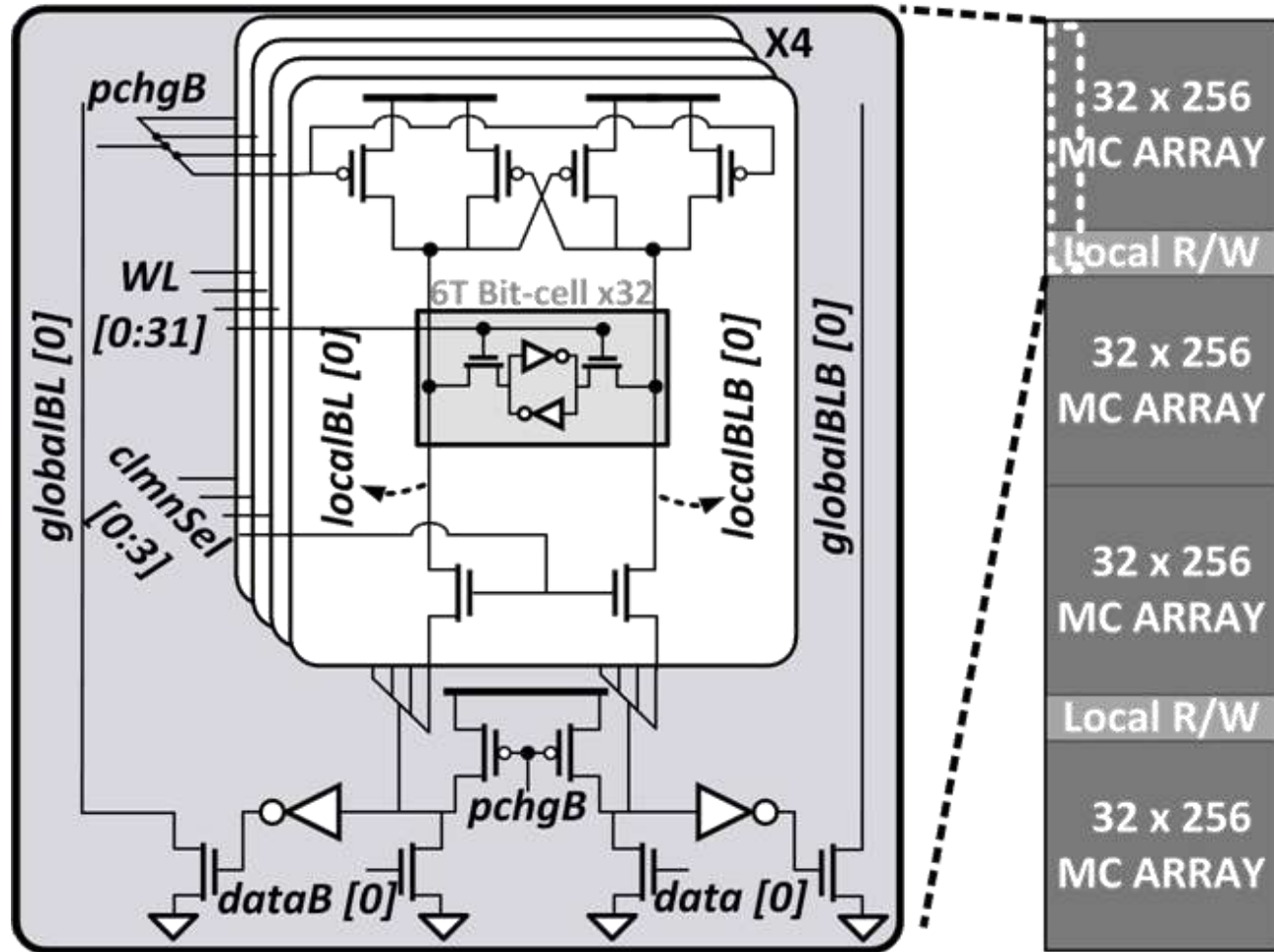
**Goal: High-density standard 6T bit-cell with peripheral assist circuits for low-voltage operation**

# Outline

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- **Array architecture**
- **Peripheral assist circuits**
- **Test chip measurement results**
- **Conclusions**

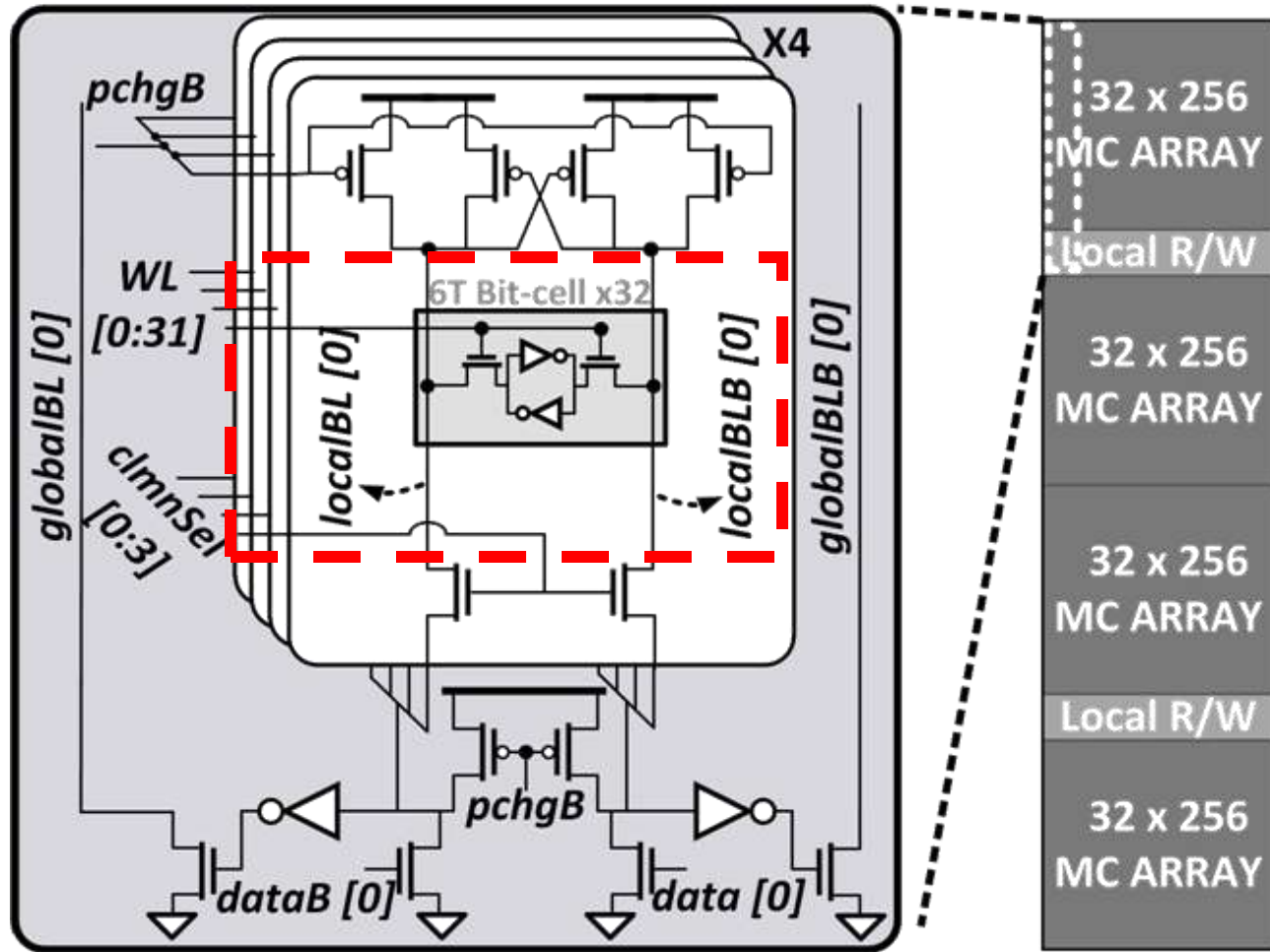
# Array Architecture



Peripheral assist circuits enable low-voltage operation

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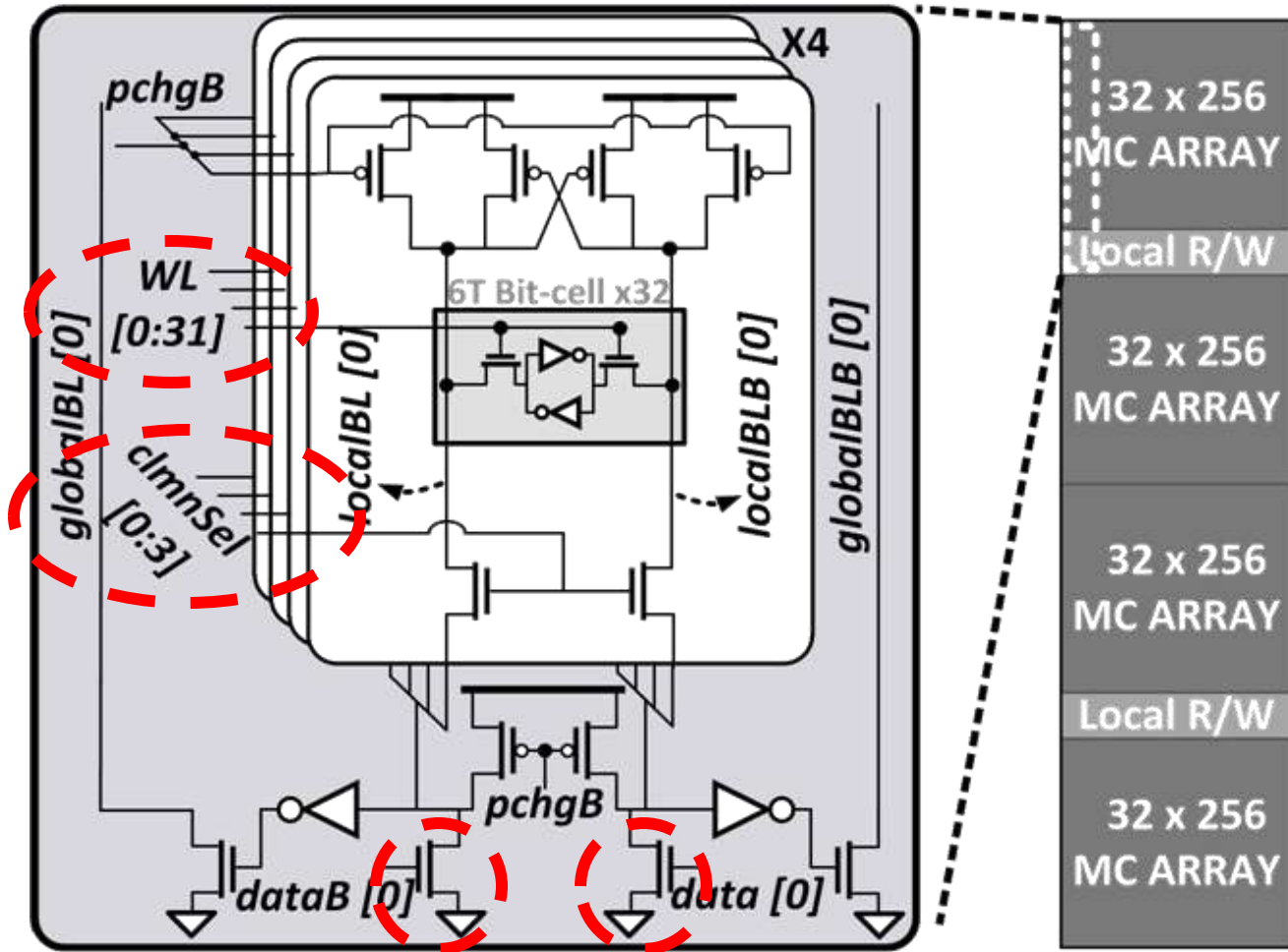
- 1) Short local bit-lines protect against read disturbs



Peripheral assist circuits enable low-voltage operation

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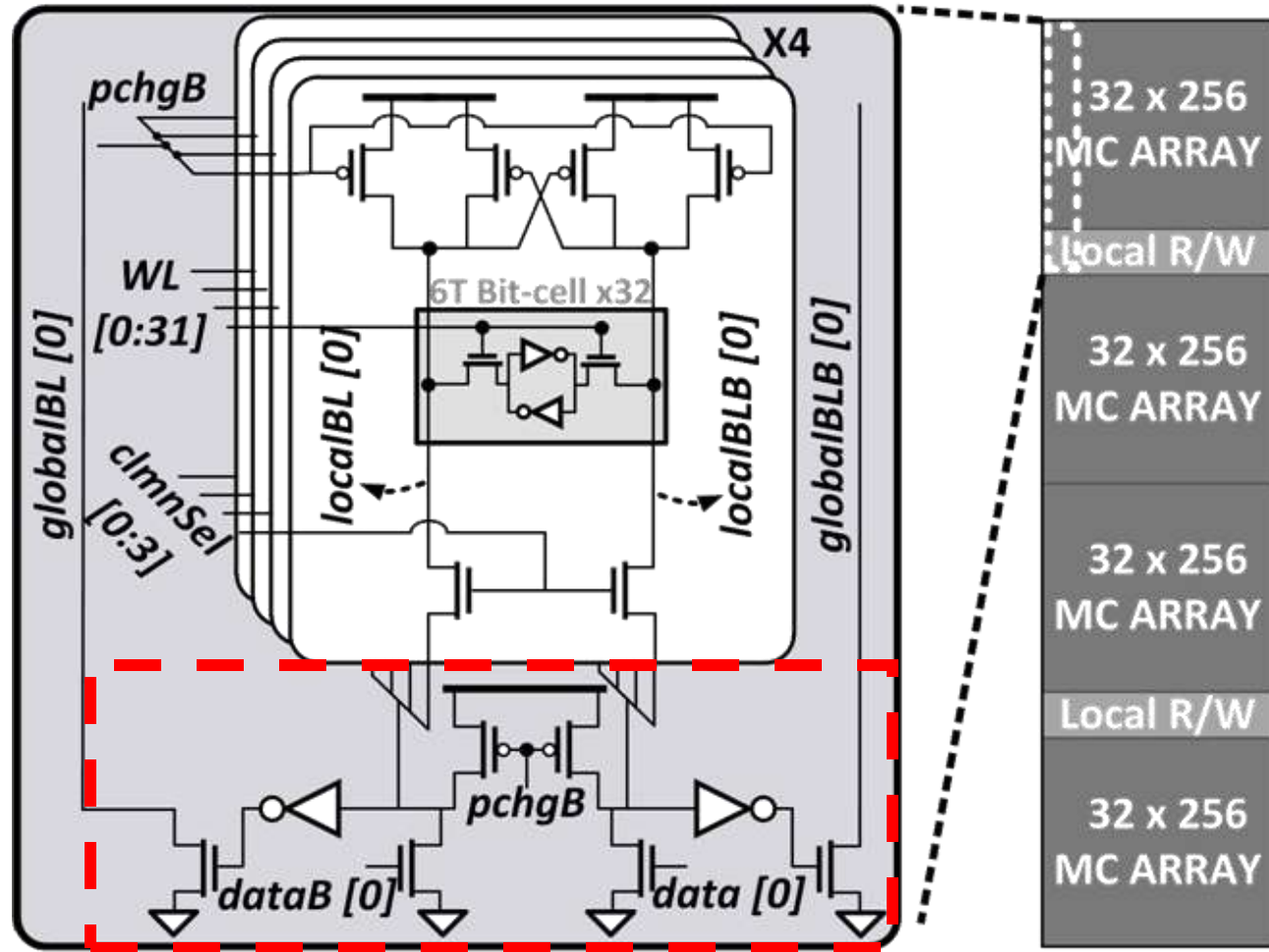
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- 2) Voltage boosting for better write-ability



Peripheral assist circuits enable low-voltage operation

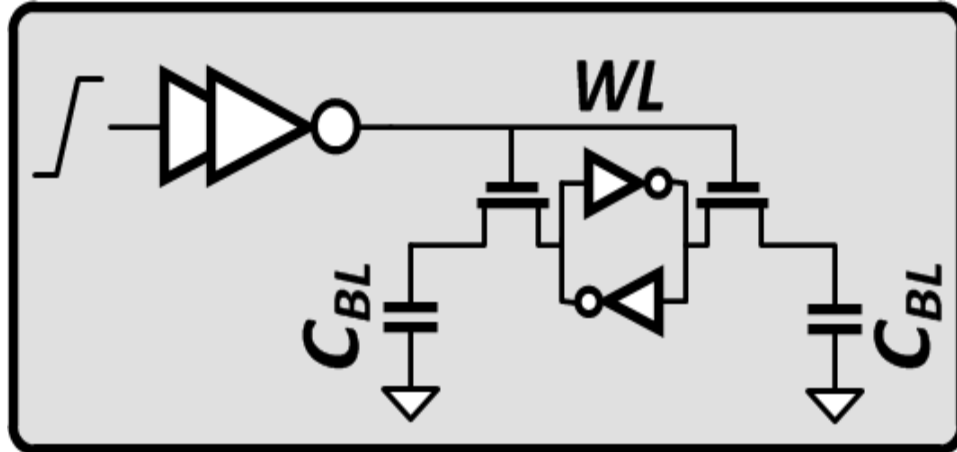
# Array Architecture

- 1) Short local bit-lines protect against read disturbs
- 2) Voltage boosting for better write-ability
- 3) Large-signal local sensing for area efficiency



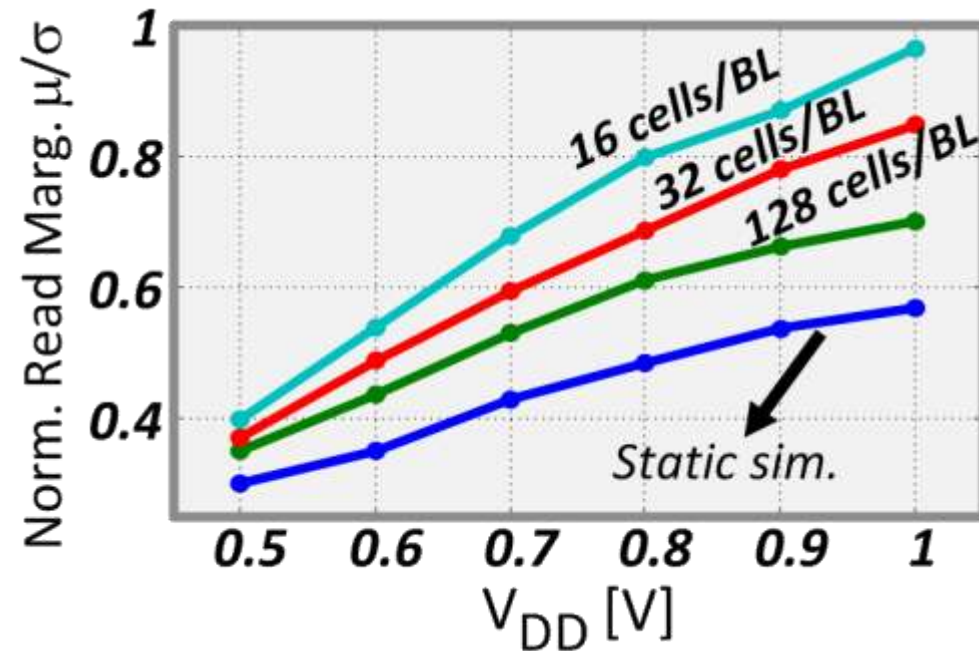
Peripheral assist circuits enable low-voltage operation

# Short BLs for Read Disturb



TRANSIENT READ MARGIN SIMULATION

*1mV accuracy with three-step search*



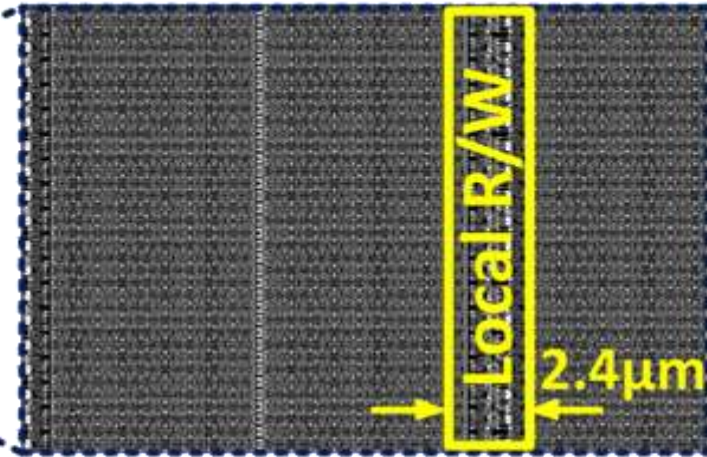
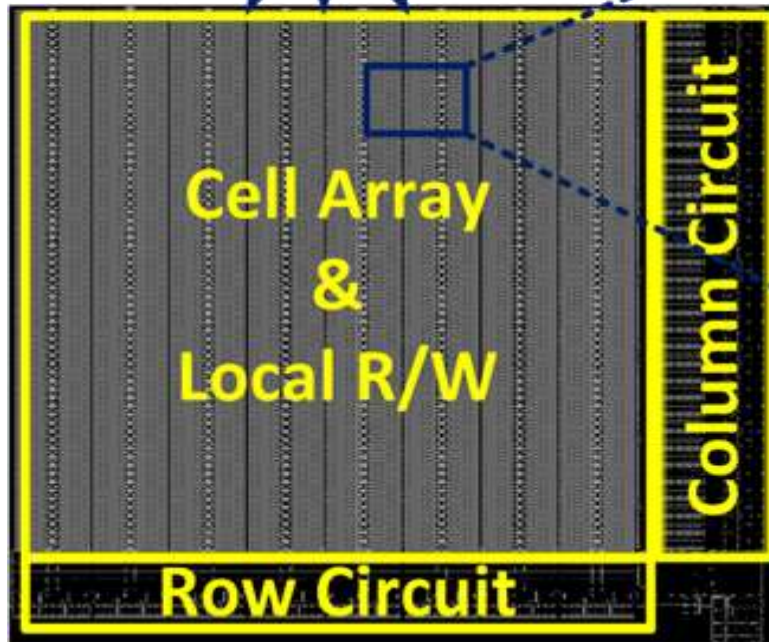
Significant read margin improvement with shorter bit-lines

This Work: 32 cells/BL

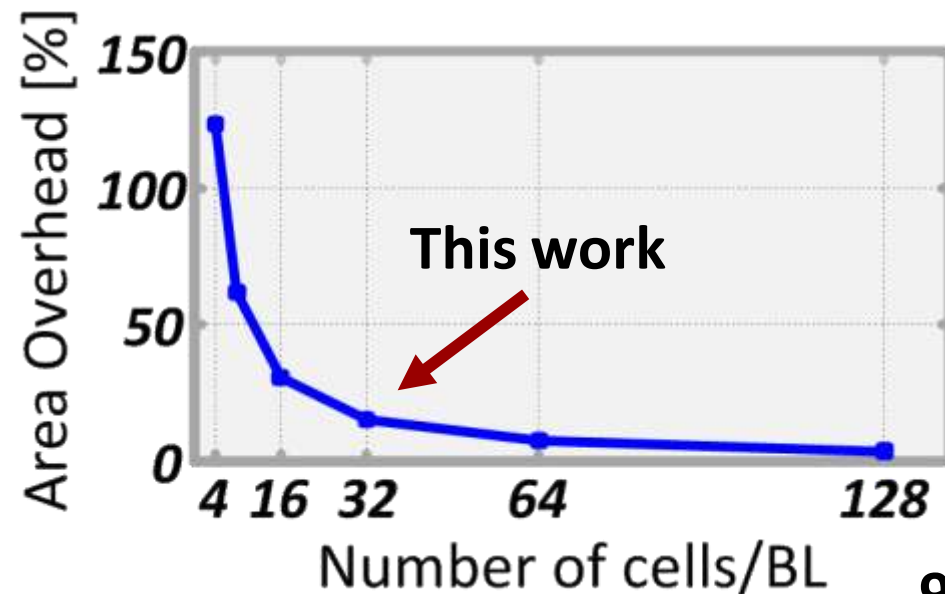


# Local R/W Circuit Area Impact

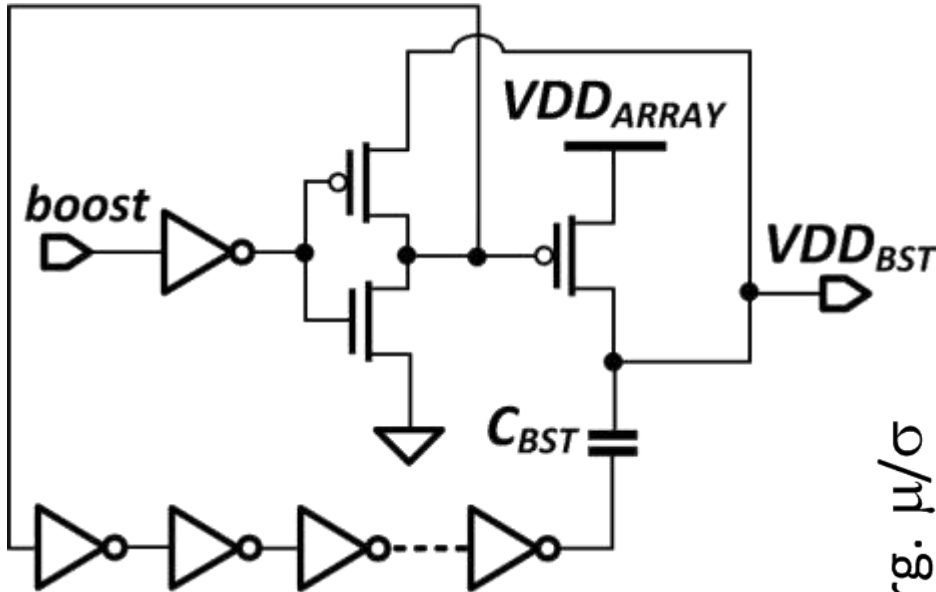
Substrate Contact Strips



15% area overhead is achieved by careful sizing and layout of local R/W circuitry

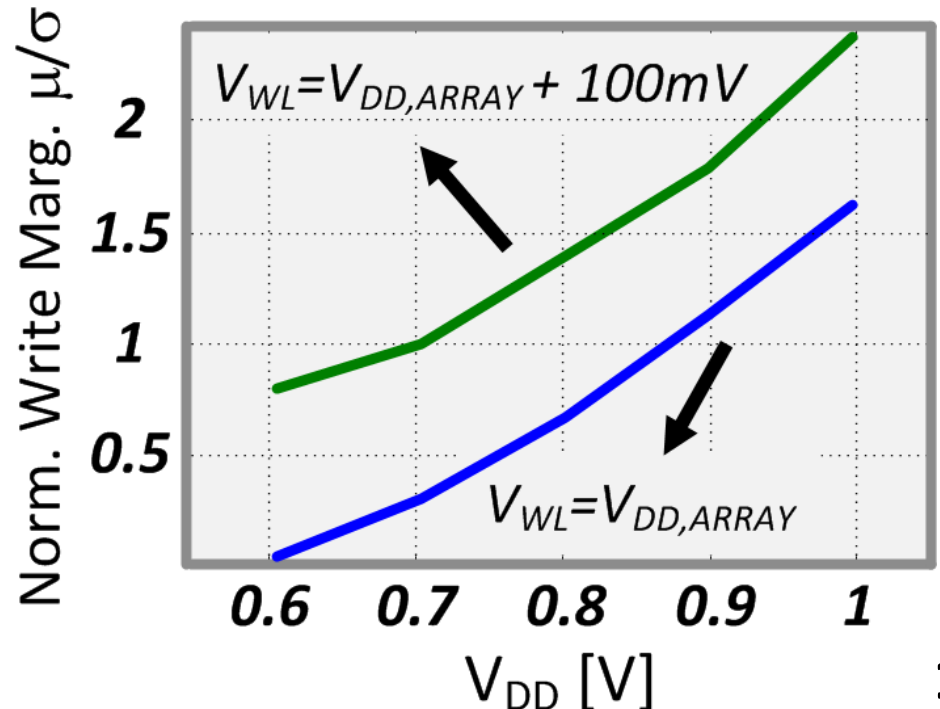


# Voltage Boosting for Write-ability



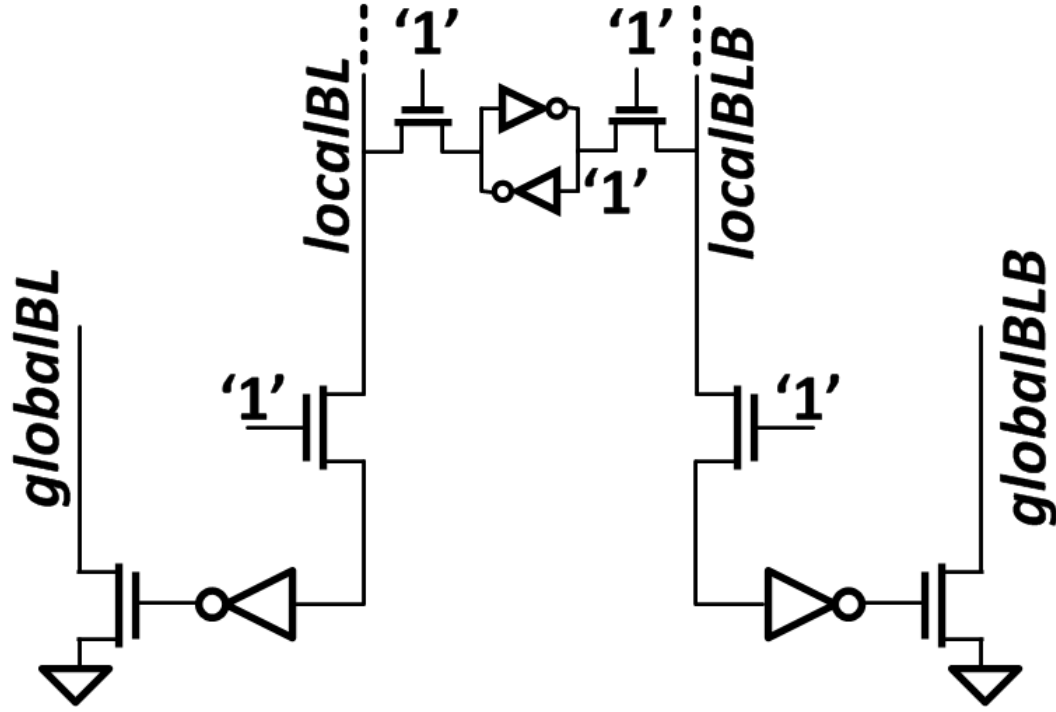
Write-ability ensured by voltage boosting through shared circuits to limit area overhead

- Boosted voltage,  $V_{DD,BST}$ , shared across all rows of a sub-block.
- *boost* signal triggered with the negative edge of *clk*



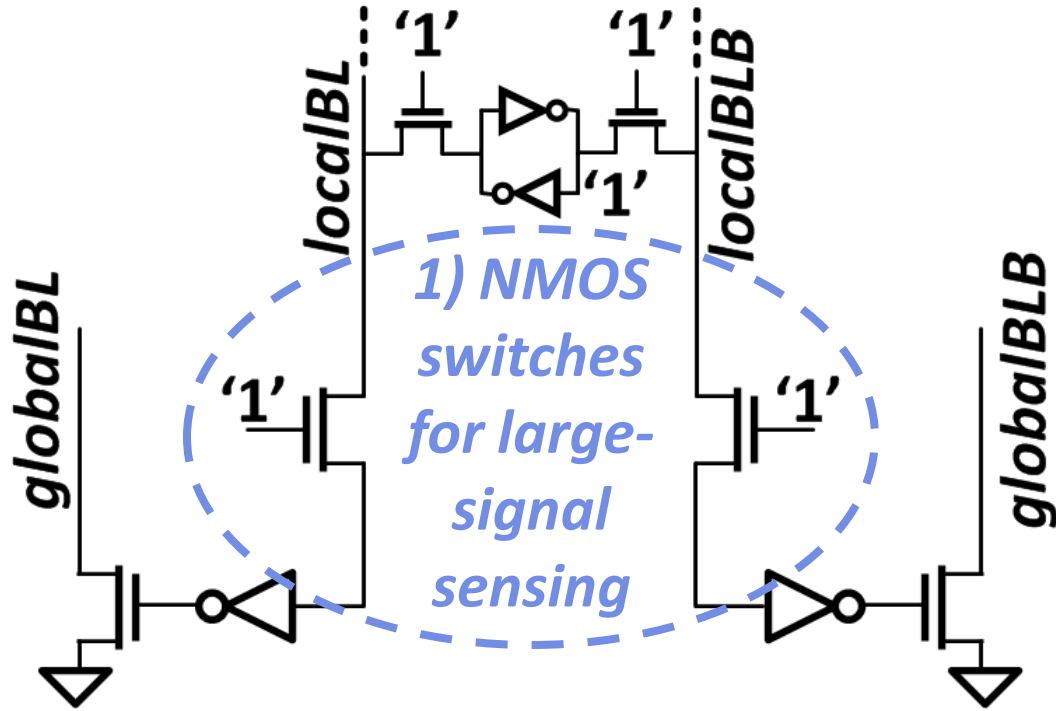
# Read Access Time Improvement

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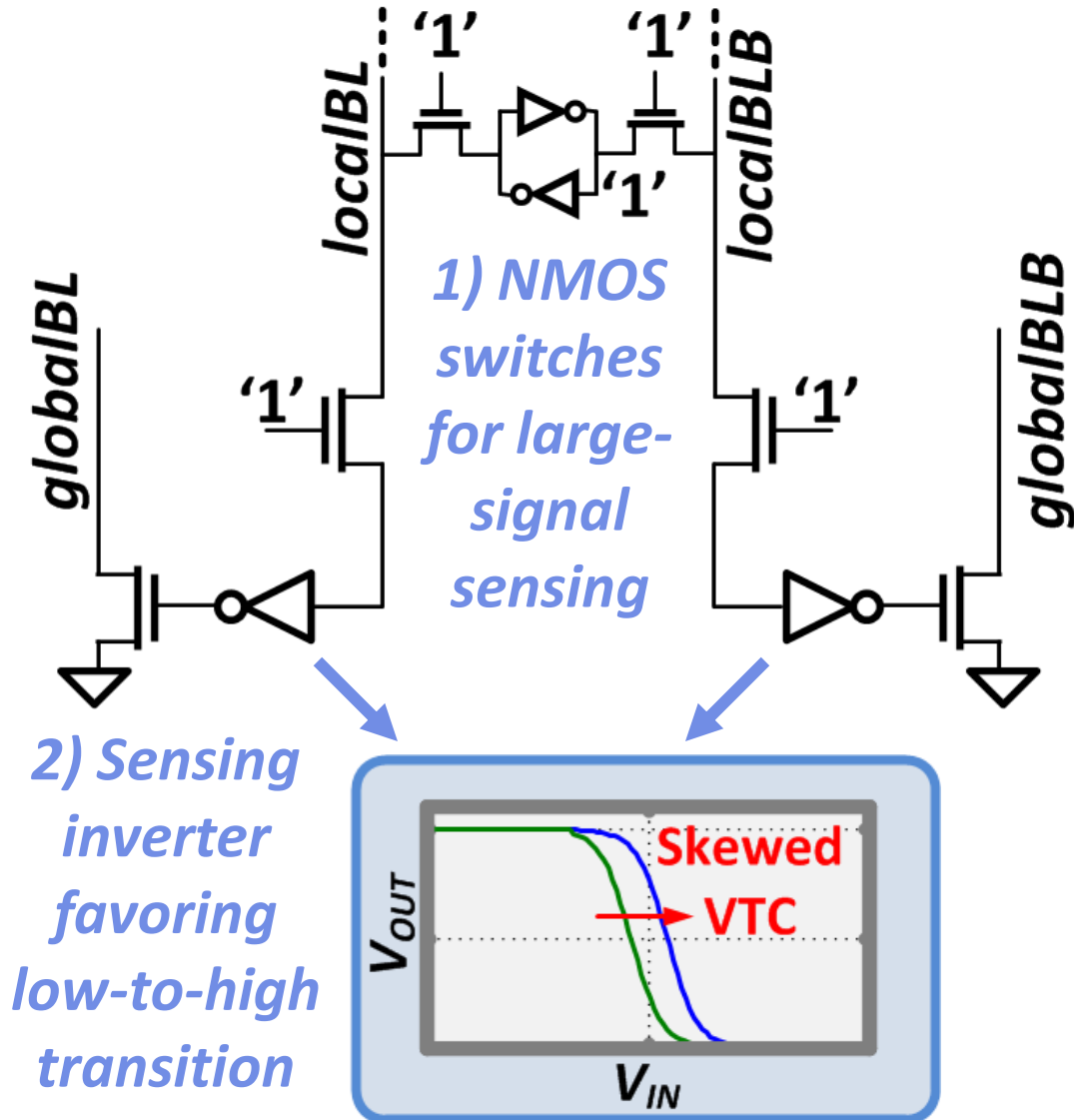


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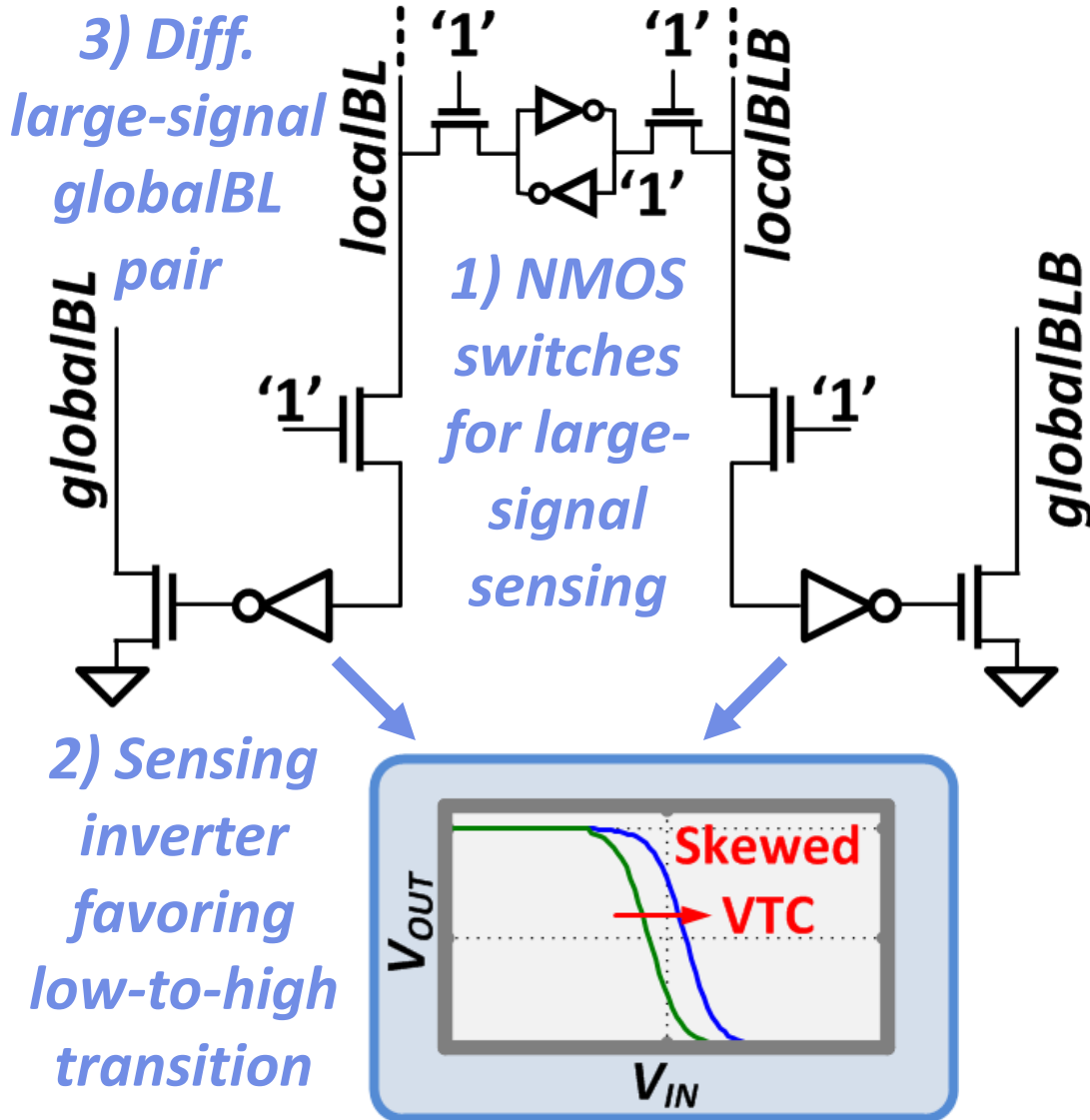
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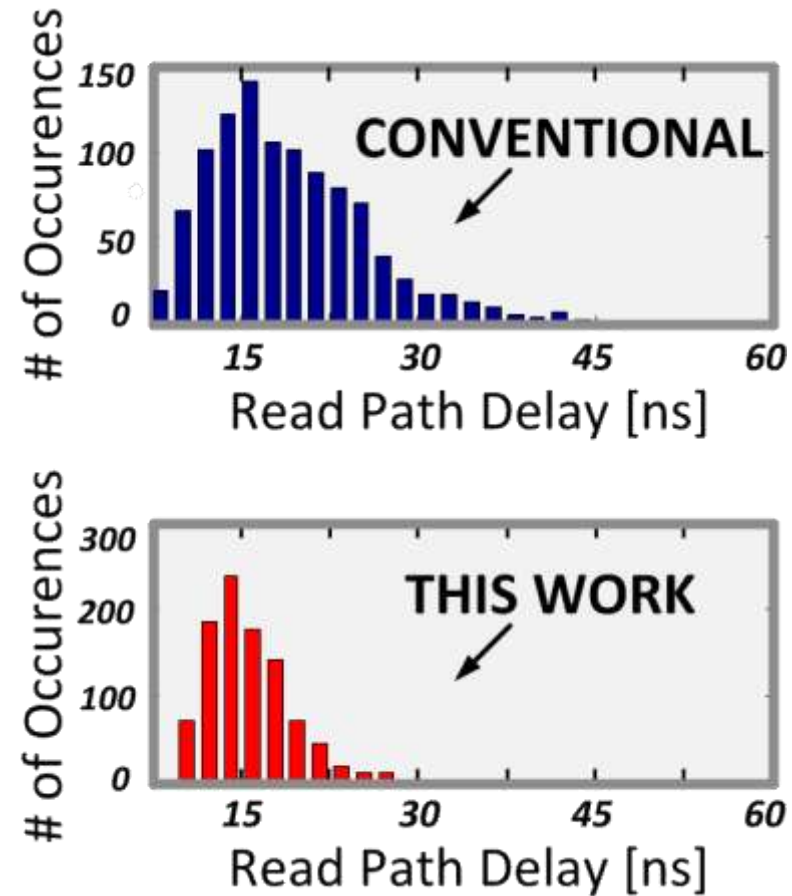
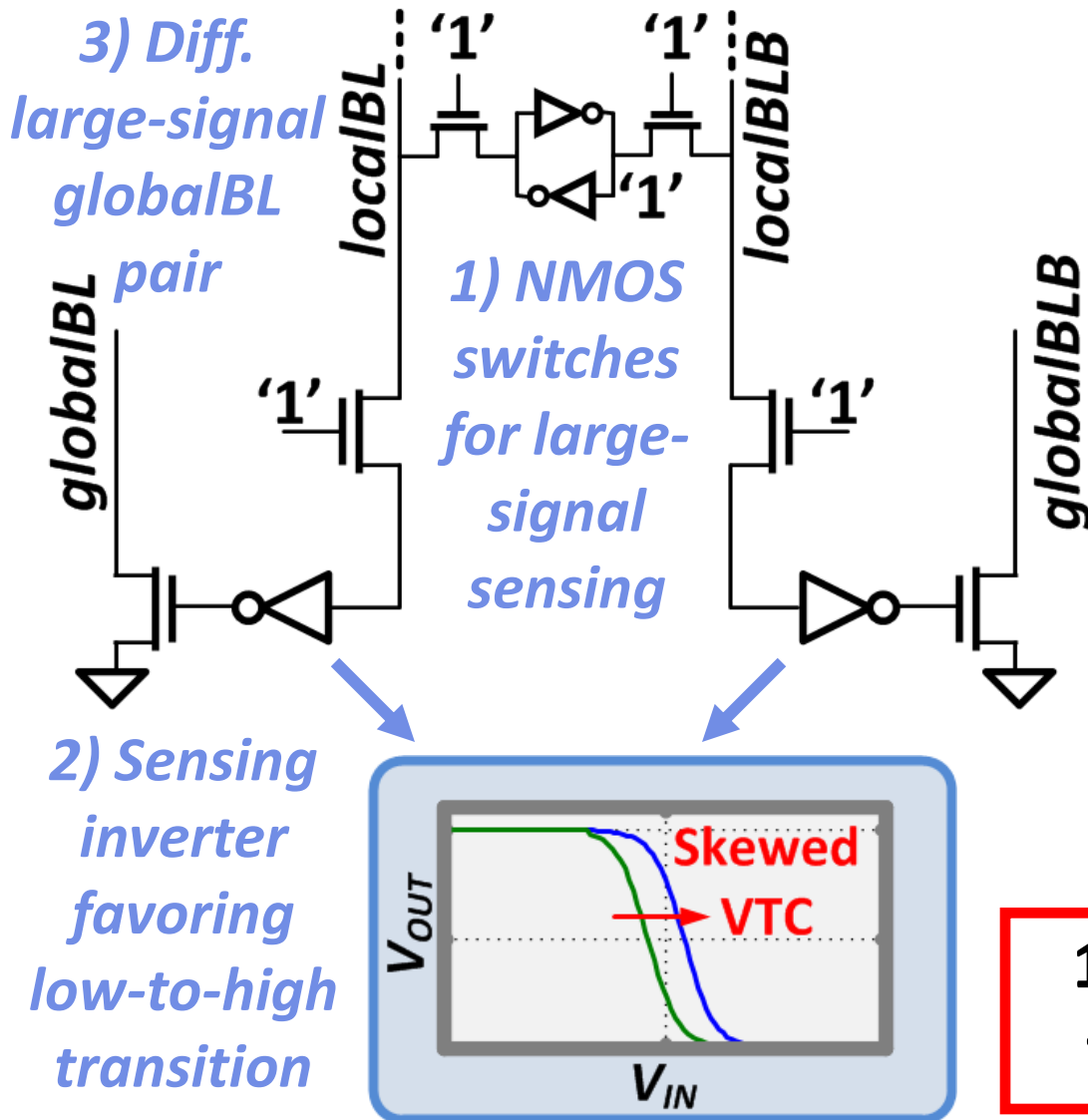
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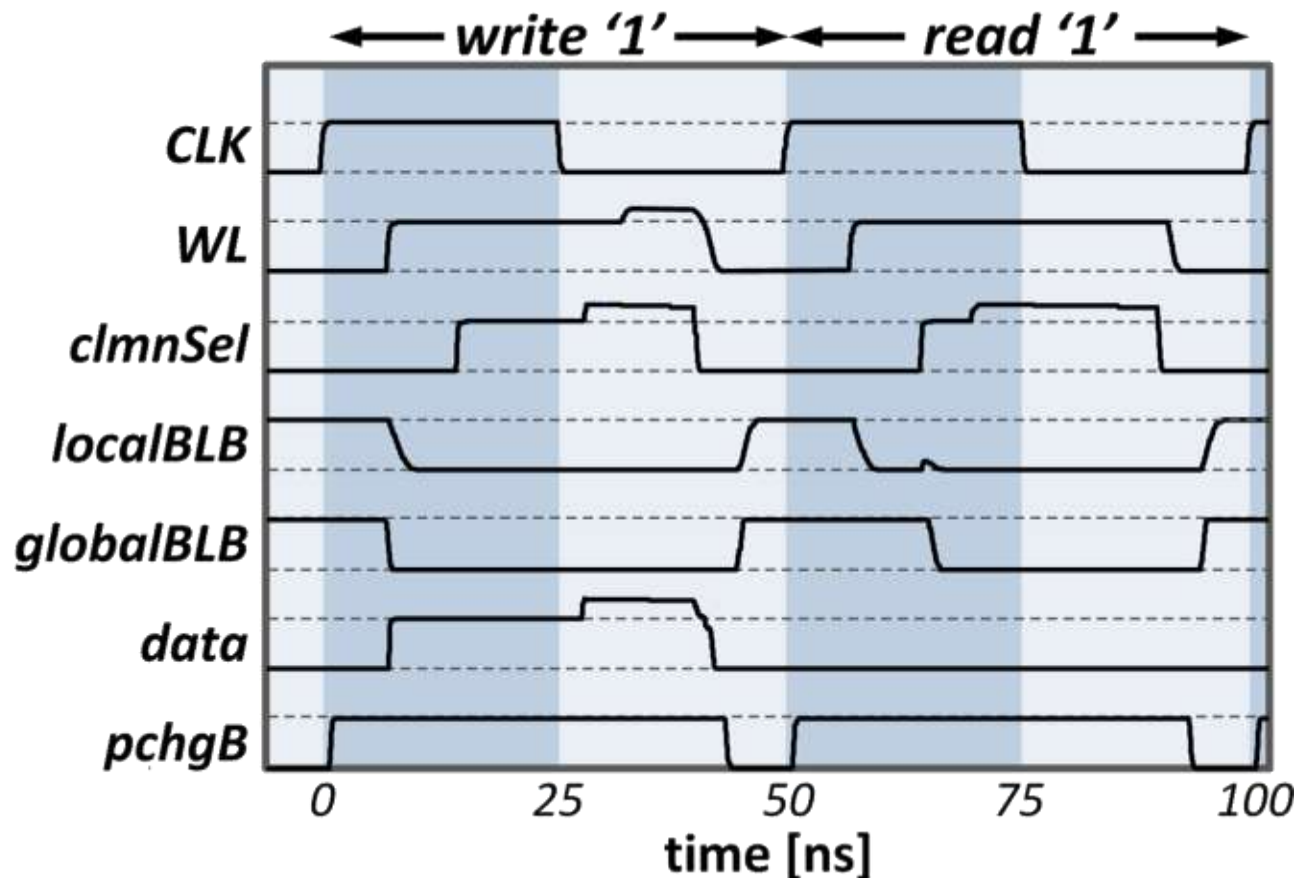
# Read Access Time Improvement



**1.8X faster read access time achieved at 0.6V**

# Simulated Read/Write Waveforms

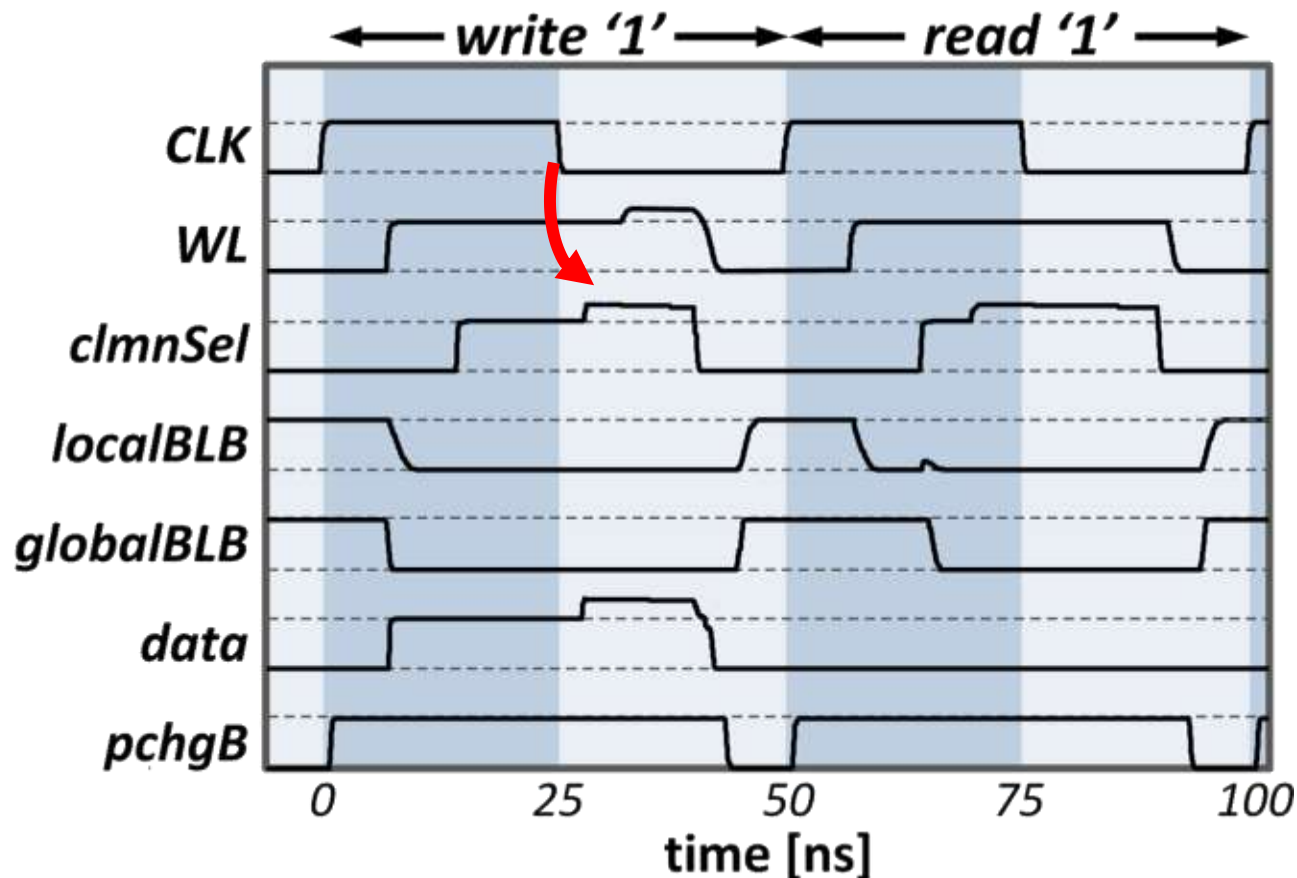
- 1) Boosted signals aligned to the negative edge of the clk
- 2) During read, *clmnSel* is turned on after a short delay, exposing bit-cell to a smaller capacitance





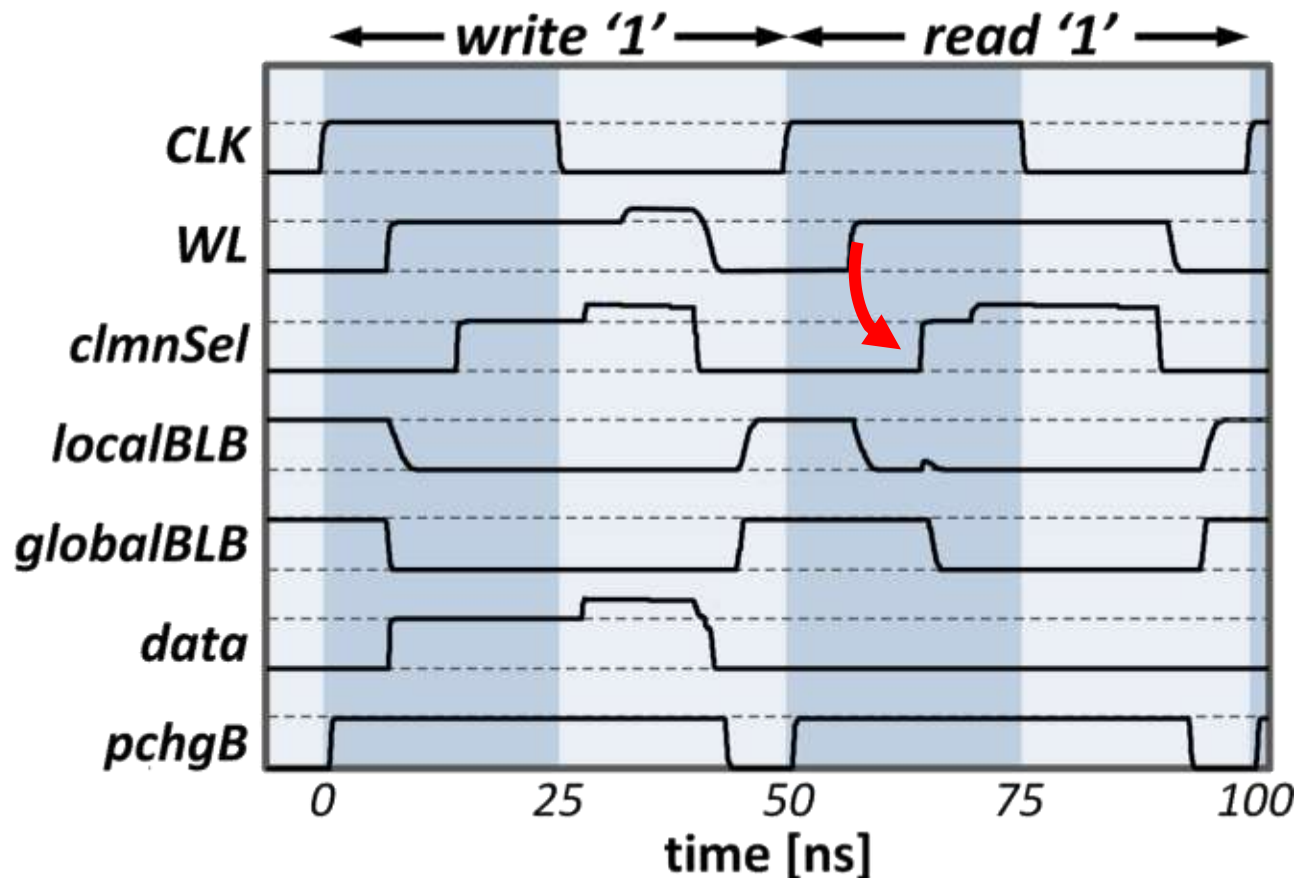
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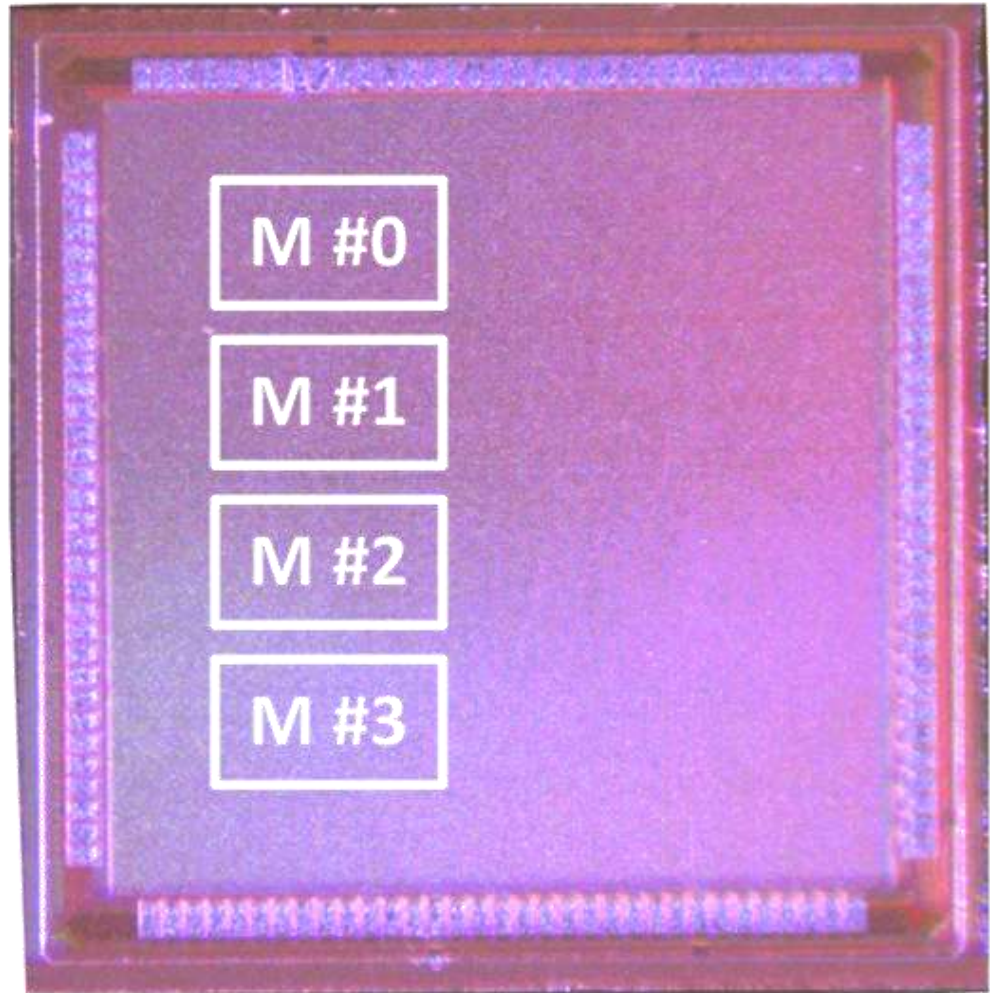
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# Test Chip Summary

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- **28nm Low Standby Power CMOS Process**
- **0.12 $\mu\text{m}^2$  6T bit-cell**
- **Die size: 2.3mm x 2.3mm**
- **Voltage Range: 0.6 to 1V**
- **Module Size: 128kbit**

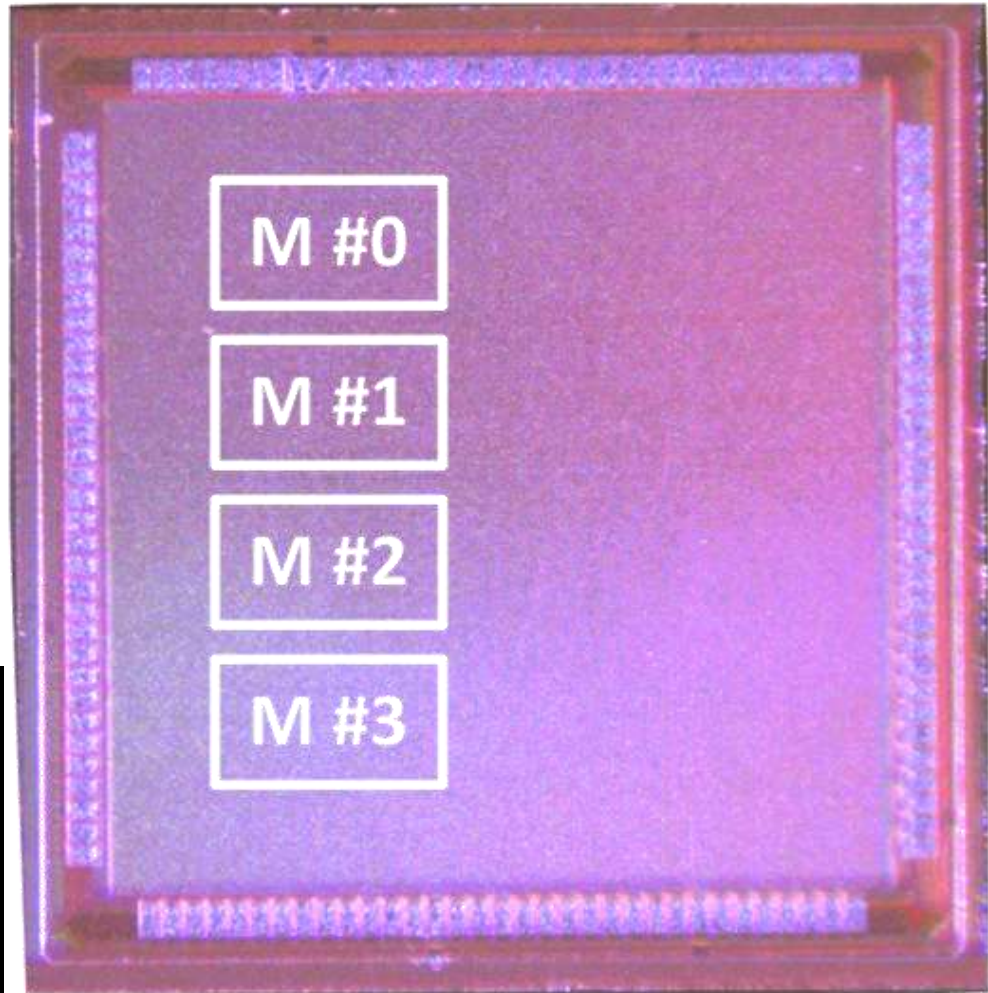


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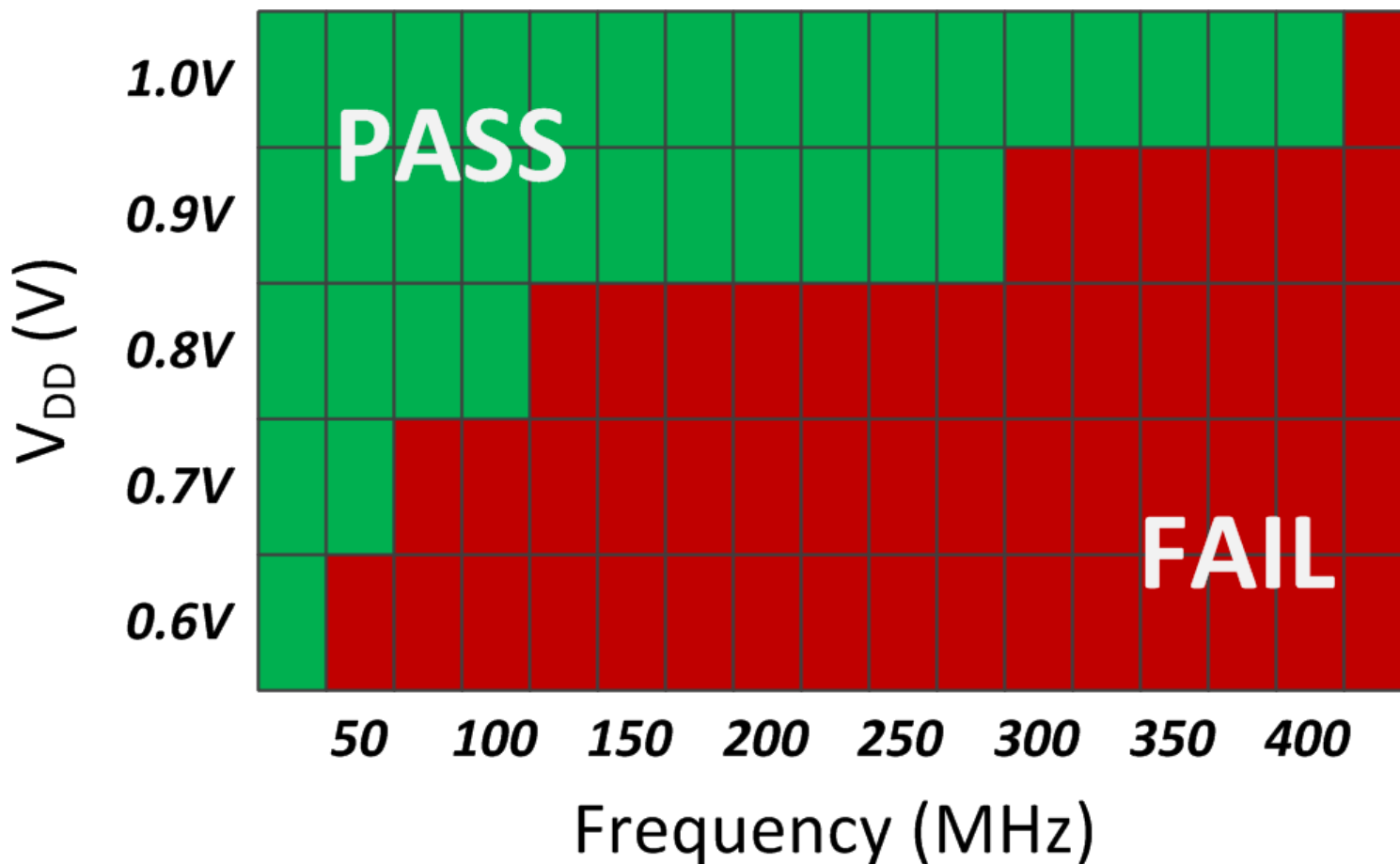
**SRAM blocks in this work are also used in a separate DSP chip:**

*Paper 7.5: A 28nm 0.6V Low-Power DSP for Mobile Applications*



# Measured Performance

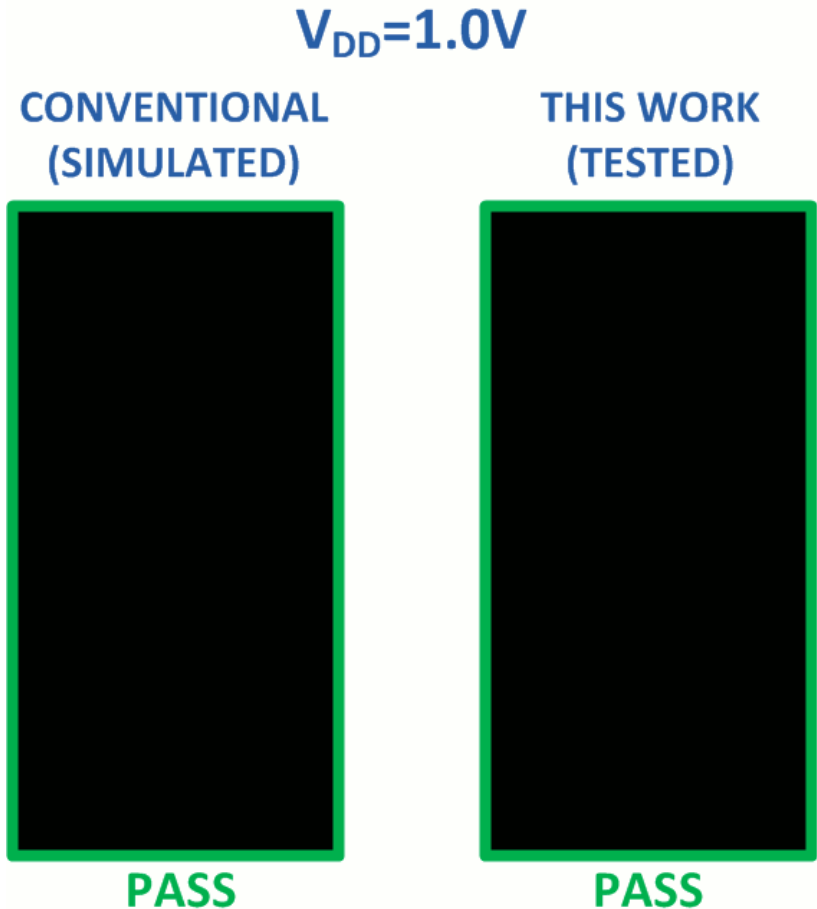
Performance scales from 400MHz to 20MHz



# Measured Bit Error Map

- Physical location of bit-cells in the memory array
- 512 Rows x 256 Columns
- Read and write failures (\*) in the conventional array due to transistor variation

(\*) White color represents failed bits



**Proposed techniques extend operating voltage range  
from 0.9V to 0.6V**

# Conclusions

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- **28nm 6T SRAM constructed with high-density  $0.12\mu\text{m}^2$  bit-cell**
- **0.6V operation is achieved through peripheral assist circuits**
- **Area-efficient alternative to the 8T SRAMs for low voltage systems**

Acknowledgement: Funding and IC fabrication provided by Texas Instruments, Incorporated

# End

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